

L Number	Hits	Search Text	DB	Time stamp
1	30183	micromachin\$3 or microelectromechanic\$3 or micro adj2 device	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:25
2	34227	(micromachin\$3 or microelectromechanic\$3 or micro adj2 device) or micro adj1 machin\$3 or micro adj1 electromechanic\$3	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:21
3	34468	((micromachin\$3 or microelectromechanic\$3 or micro adj2 device) or micro adj1 machin\$3 or micro adj1 electromechanic\$3 ) or (thermo adj2 optic\$4 or thermo optic\$4) adj3 switch\$3	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:24
4	775440	gap\$3	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:26
5	3410	thermal\$3 near20 isolat\$4 near20 substrate	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:27
6	89	gap\$3 same (thermal\$3 near20 isolat\$4 near20 substrate)	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:27
7	28	(gap\$3 same (thermal\$3 near20 isolat\$4 near20 substrate)) and ((micromachin\$3 or microelectromechanic\$3 or micro adj2 device) or micro adj1 machin\$3 or micro adj1 electromechanic\$3 ) or (thermo adj2 optic\$4 or thermo optic\$4) adj3 switch\$3)	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:27

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3	34468	((micromachin\$3 or microelectromechanic\$3 or micro adj2 device) or micro adj1 machin\$3 or micro adj1 electromechanic\$3 ) or (thermo adj2 optic\$4 or thermooptic\$4) adj3 switch\$3	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:24
4	775440	gap\$3	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:26
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7	28	(gap\$3 same (thermal\$3 near20 isolat\$4 near20 substrate)) and (((micromachin\$3 or microelectromechanic\$3 or micro adj2 device) or micro adj1 machin\$3 or micro adj1 electromechanic\$3 ) or (thermo adj2 optic\$4 or thermooptic\$4) adj3 switch\$3)	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:32
8	18813	thermal\$3 near20 isolat\$4	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:33
9	760	gap\$3 same (thermal\$3 near20 isolat\$4)	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:33
10	55	(gap\$3 same (thermal\$3 near20 isolat\$4)) and (((micromachin\$3 or microelectromechanic\$3 or micro adj2 device) or micro adj1 machin\$3 or micro adj1 electromechanic\$3 ) or (thermo adj2 optic\$4 or thermooptic\$4) adj3 switch\$3)	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:33
11	27	((gap\$3 same (thermal\$3 near20 isolat\$4)) and (((micromachin\$3 or microelectromechanic\$3 or micro adj2 device) or micro adj1 machin\$3 or micro adj1 electromechanic\$3 ) or (thermo adj2 optic\$4 or thermooptic\$4) adj3 switch\$3)) not ((gap\$3 same (thermal\$3 near20 isolat\$4 near20 substrate)) and (((micromachin\$3 or microelectromechanic\$3 or micro adj2 device) or micro adj1 machin\$3 or micro adj1 electromechanic\$3 ) or (thermo adj2 optic\$4 or thermooptic\$4) adj3 switch\$3))	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/03 17:34

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1	1283145	gap\$3 or cavit\$3	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/04 10:21
2	2471169	insulat\$3 or dielectric or sio2 or sio or oxide or dioxide	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/04 10:22
3	3190100	etch\$3 or remov\$3	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/04 10:23
4	18813	thermal\$3 near20 isolat\$4	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/04 10:25
5	128	(gap\$3 or cavit\$3) same (insulat\$3 or dielectric or sio2 or sio or oxide or dioxide) same (etch\$3 or remov\$3) same (thermal\$3 near20 isolat\$4)	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/04 10:26
6	34227	((micromachin\$3 or microelectromechanic\$3 or micro adj2 device) or micro adj1 machin\$3 or micro adj1 electromechanic\$3 ) or (thermo adj2 optic\$4 or thermooptic\$4) adj3 switch\$3 and ((gap\$3 or cavit\$3) same (insulat\$3 or dielectric or sio2 or sio or oxide or dioxide) same (etch\$3 or remov\$3) same (thermal\$3 near20 isolat\$4))	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/04 10:29
7	34468	((micromachin\$3 or microelectromechanic\$3 or micro adj2 device) or micro adj1 machin\$3 or micro adj1 electromechanic\$3 ) or (thermo adj2 optic\$4 or thermooptic\$4) adj3 switch\$3	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/04 10:33
8	32	((gap\$3 or cavit\$3) same (insulat\$3 or dielectric or sio2 or sio or oxide or dioxide) same (etch\$3 or remov\$3) same (thermal\$3 near20 isolat\$4)) and (((micromachin\$3 or microelectromechanic\$3 or micro adj2 device) or micro adj1 machin\$3 or micro adj1 electromechanic\$3 ) or (thermo adj2 optic\$4 or thermooptic\$4) adj3 switch\$3)	USPAT; US-PGPUB; JPO; DERWENT; IBM_TDB	2003/03/04 10:33